AOT66914L/AOB66914L

100V N-Channel AlphaSGT™

General Description

- Trench Power MOSFET - AlphaSGT™ technology
- Extremely Low $R_{DS(ON)}$
- Optimized switching performance
- 175°C operating temperature
- RoHS and Halogen-Free Compliant

Product Summary

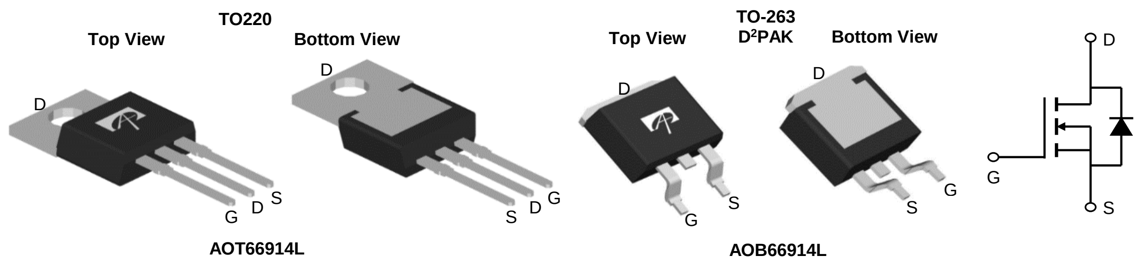
V_{DS}	100V
I_D (at V_{GS}=10V)	120A
$R_{DS(ON)}$ (at V_{GS}=10V)	< 2.7mΩ
$R_{DS(ON)}$ (at V_{GS}=6V)	< 3.5mΩ

100% UIS Tested
100% Rg Tested

Max Tj=175°C

Applications

- Telecom DC-DC
- Industrial power
- Load switch
- Telecom Hot-Swap



Orderable Part Number	Package Type	Form	Minimum Order Quantity
AOT66914L	TO-220	Tube	1000
AOB66914L	TO-263	Tape & Reel	800

Absolute Maximum Ratings T_A=25°C unless otherwise noted

Parameter		Symbol	Maximum	Units
Drain-Source Voltage		V_{DS}	100	V
Gate-Source Voltage		V_{GS}	±20	V
Continuous Drain Current	T_C=25°C	I_D	120	A
	T_C=100°C		120	
Pulsed Drain Current [C]		I_{DM}	480	
Continuous Drain Current	T_A=25°C	I_{DSM}	45	A
	T_A=70°C		38	
Avalanche Current [C]		I_{AS}	90	A
Avalanche energy	L=0.1mH [C]	E_{AS}	405	mJ
Power Dissipation [B]	T_C=25°C	P_D	375	W
	T_C=100°C		185	
Power Dissipation [A]	T_A=25°C	P_{DSM}	10	W
	T_A=70°C		7	
Junction and Storage Temperature Range		T_J, T_{STG}	-55 to 175	°C

Thermal Characteristics

Parameter		Symbol	Typ	Max	Units
Maximum Junction-to-Ambient [A]	t ≤ 10s	$R_{θJA}$	12	15	°C/W
Maximum Junction-to-Ambient [A D]	Steady-State		50	60	°C/W
Maximum Junction-to-Case	Steady-State	$R_{θJC}$	0.26	0.40	°C/W

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions		Min	Typ	Max	Units
STATIC PARAMETERS							
BV_{DSS}	Drain-Source Breakdown Voltage	I_D=250µA, V_{GS}=0V		100			V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=100V, V_{GS}=0V				1	µA
			T_J=55°C			5	
I_{GSS}	Gate-Body leakage current	V_{DS}=0V, V_{GS}=±20V				±100	nA
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_D=250µA		2.5	3.0	3.5	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=10V, I_D=20A			2.2	2.7	mΩ
			T_J=125°C		3.6	4.5	
		V_{GS}=6V, I_D=20A			2.7	3.5	mΩ
g_{FS}	Forward Transconductance	V_{DS}=5V, I_D=20A			68		S
V_{SD}	Diode Forward Voltage	I_S=1A, V_{GS}=0V			0.7	1	V
I_S	Maximum Body-Diode Continuous Current[G]					120	A
DYNAMIC PARAMETERS							
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=50V, f=1MHz			12500		pF
C_{oss}	Output Capacitance				3190		pF
C_{rss}	Reverse Transfer Capacitance				55		pF
R_g	Gate resistance	f=1MHz		0.8	1.75	2.7	Ω
SWITCHING PARAMETERS							
Q_g(10V)	Total Gate Charge	V_{GS}=10V, V_{DS}=50V, I_D=20A			155	220	nC
Q_{gs}	Gate Source Charge				48		nC
Q_{gd}	Gate Drain Charge				31		nC
Q_{oss}	Output Charge	V_{GS}=0V, V_{DS}=50V			269		nC
$t_{D(on)}$	Turn-On DelayTime	V_{GS}=10V, V_{DS}=50V, R_L=2.5Ω, R_{GEN}=3Ω			36		ns
t_r	Turn-On Rise Time				25		ns
$t_{D(off)}$	Turn-Off DelayTime				90		ns
t_f	Turn-Off Fall Time				40		ns
t_{rr}	Body Diode Reverse Recovery Time	I_F=20A, di/dt=500A/µs			55		ns
Q_{rr}	Body Diode Reverse Recovery Charge	I_F=20A, di/dt=500A/µs			335		nC

A. The value of $R_{\theta JA}$ is measured in a still air environment with T_A =25° C. The Power dissipation P_{DSM} is based on $R_{\theta JA}$ t≤ 10s and the maximum allowed junction temperature of 175° C. The value in any given application depends on the user's specific board design, and the maximum temperature of 175° C may be used if the PCB allows it.
B. The power dissipation P_D is based on $T_{J(MAX)}$=175° C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.
C. Single pulse width limited by junction temperature $T_{J(MAX)}$=175° C.
D. The $R_{\theta JA}$ is the sum of the thermal impedance from junction to case $R_{\theta JC}$ and case to ambient.
E. The static characteristics in Figures 1 to 6 are obtained using <300µs pulses, duty cycle 0.5% max.
F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of $T_{J(MAX)}$=175° C. The SOA curve provides a single pulse rating.
G. The maximum current rating is package limited.
H. These tests are performed in a still air environment with T_A=25° C.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

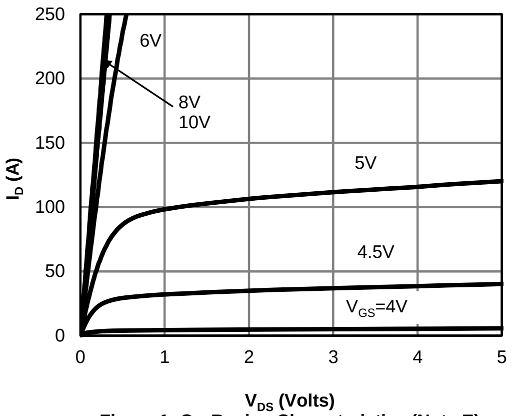


Figure 1: On-Region Characteristics (Note E)

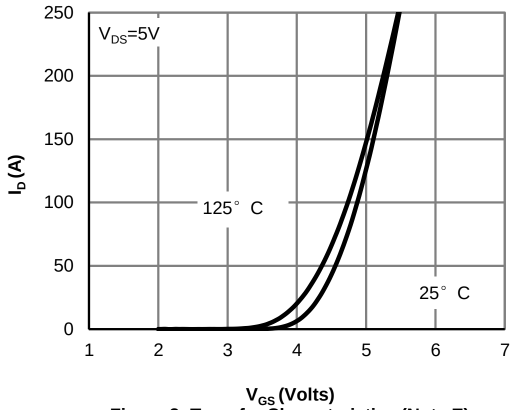


Figure 2: Transfer Characteristics (Note E)

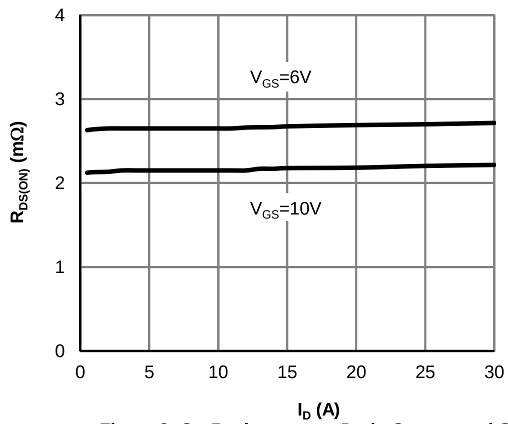


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

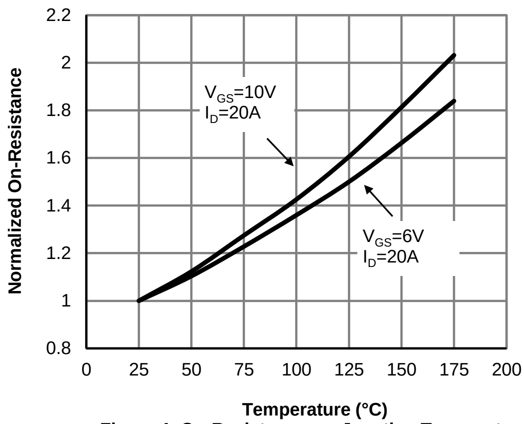


Figure 4: On-Resistance vs. Junction Temperature (Note E)

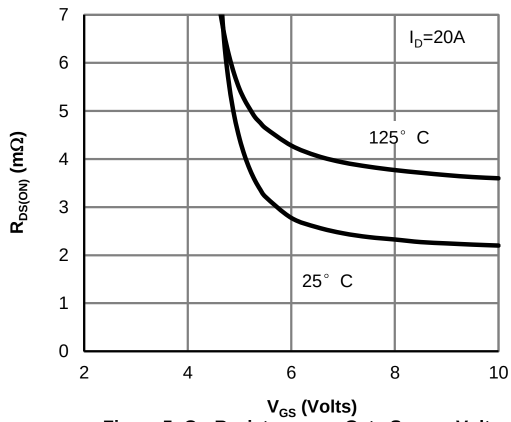


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

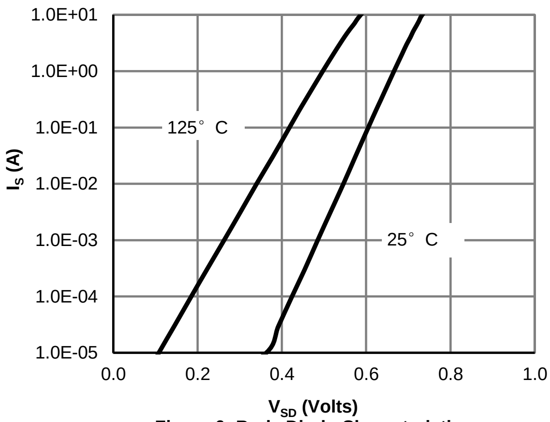


Figure 6: Body-Diode Characteristics (Note E)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

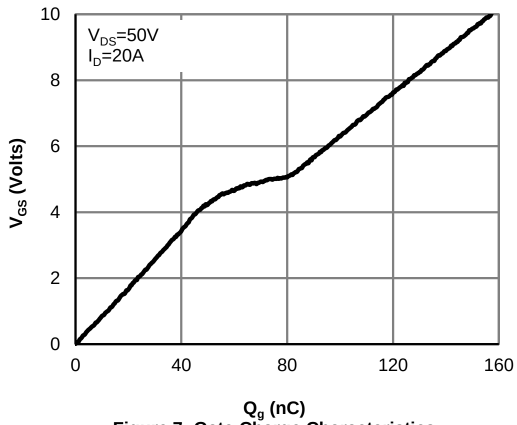


Figure 7: Gate-Charge Characteristics

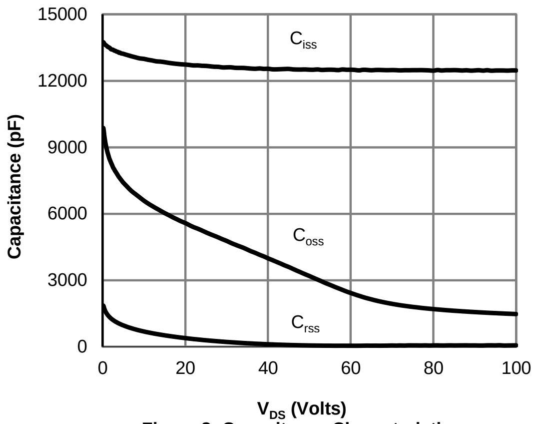


Figure 8: Capacitance Characteristics

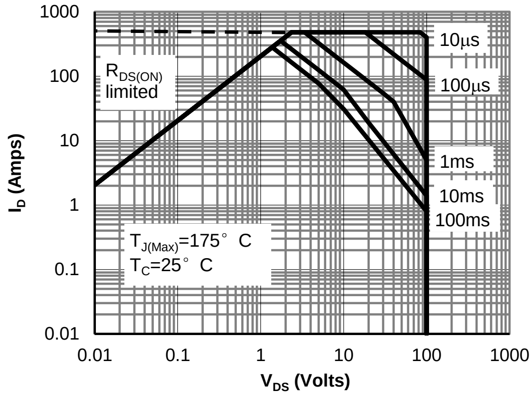


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

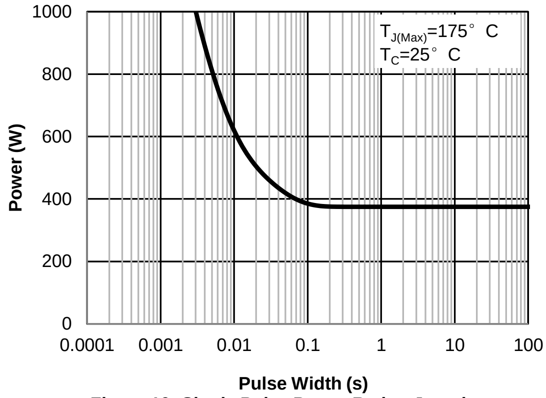


Figure 10: Single Pulse Power Rating Junction-to-Case (Note

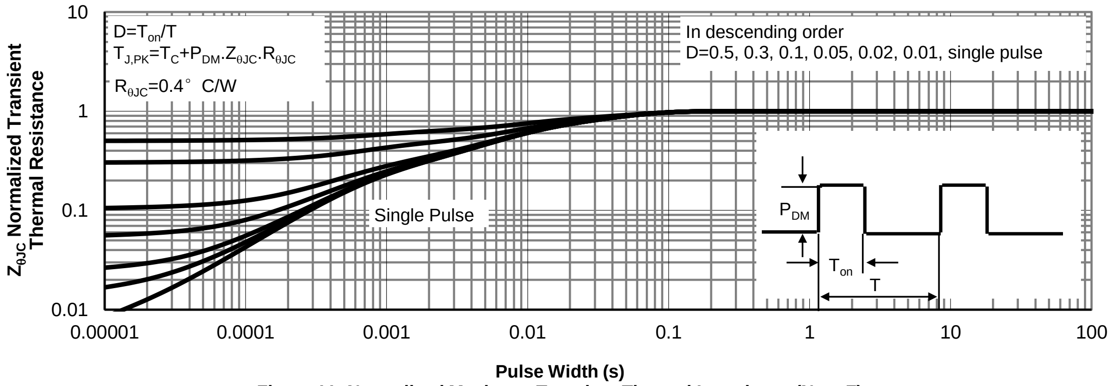


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

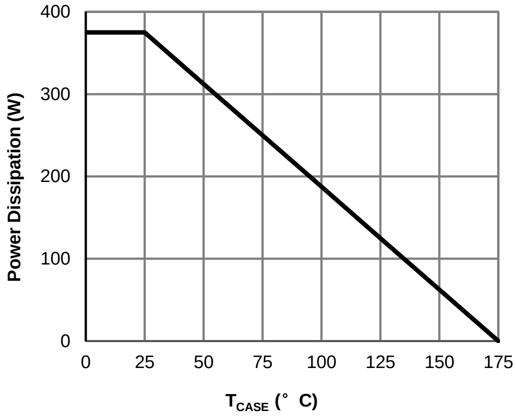


Figure 12: Power De-rating (Note F)

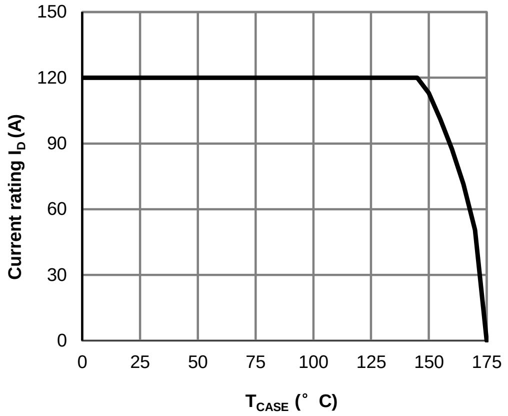


Figure 13: Current De-rating (Note F)

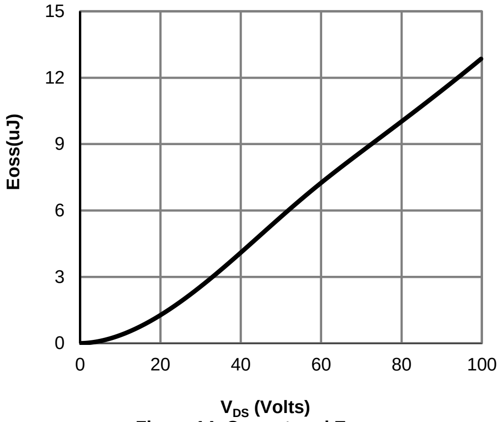


Figure 14: Coss stored Energy

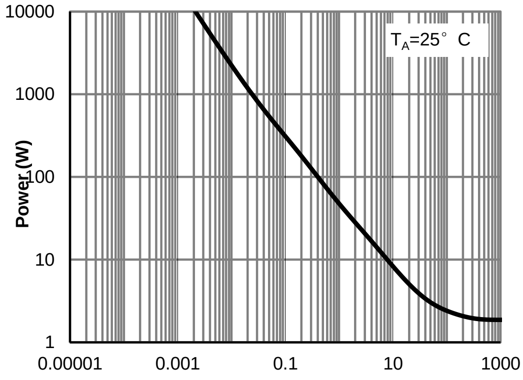


Figure 15: Single Pulse Power Rating Junction-to-Ambient (Note H)

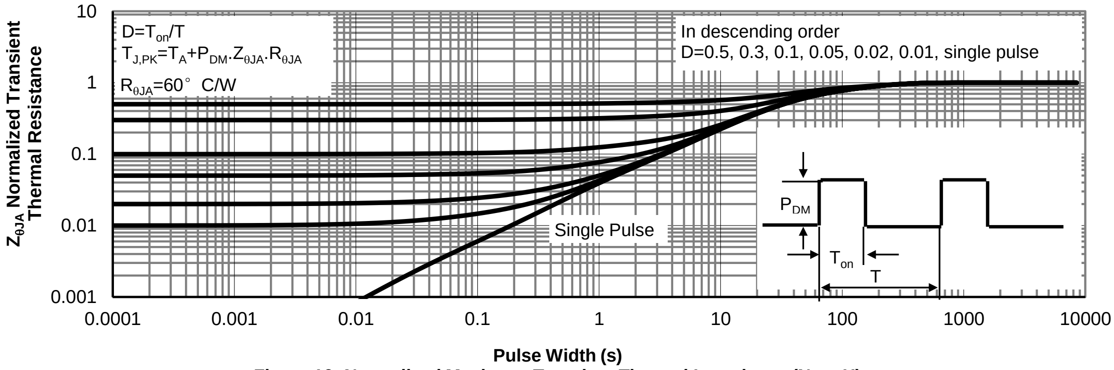


Figure 16: Normalized Maximum Transient Thermal Impedance (Note H)

Figure A: Gate Charge Test Circuit & Waveforms

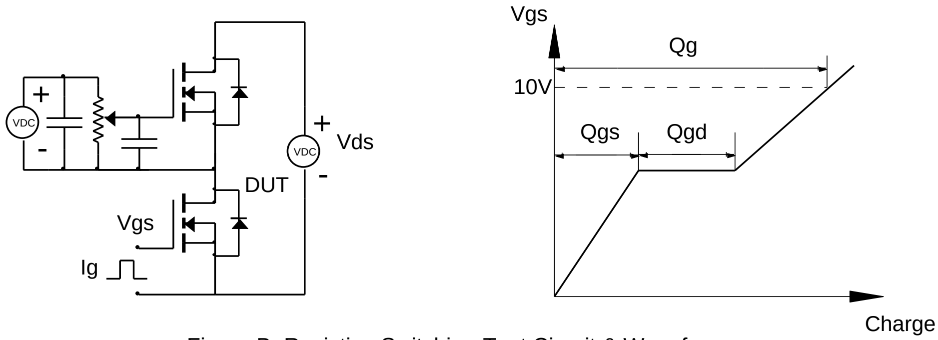


Figure B: Resistive Switching Test Circuit & Waveforms

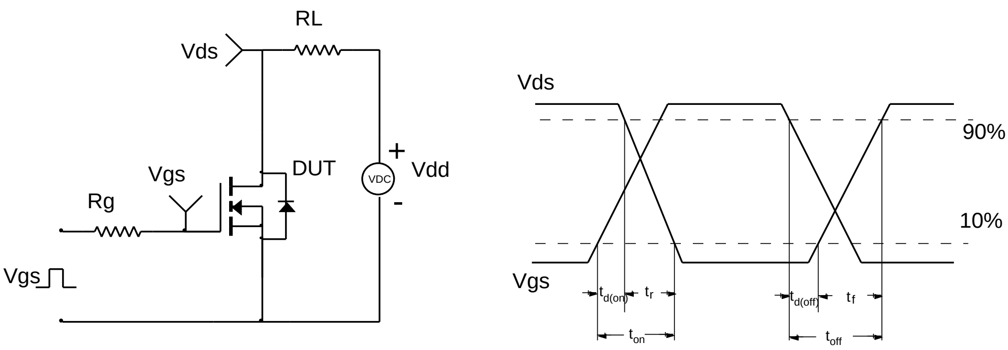


Figure C: Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

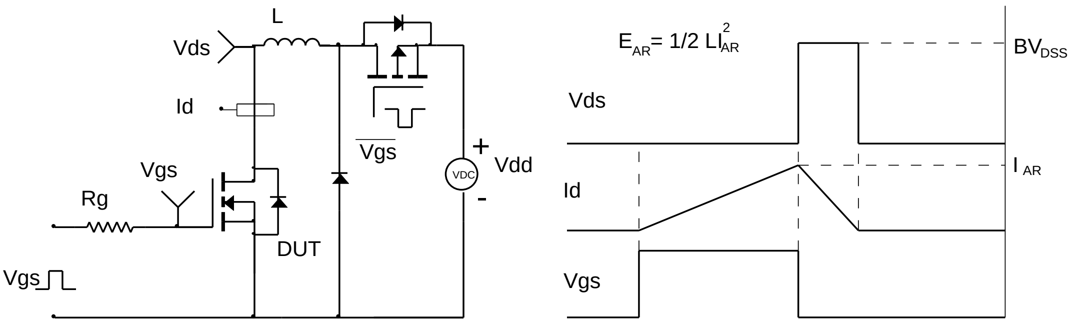


Figure D: Diode Recovery Test Circuit & Waveforms